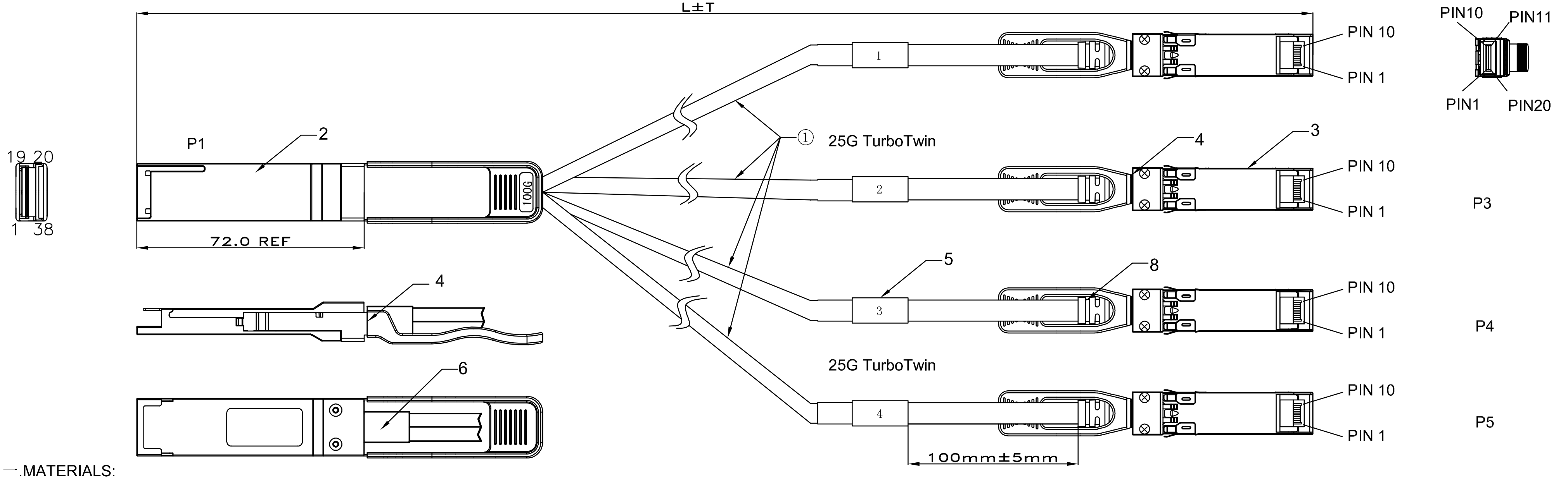


一.MATERIALS:

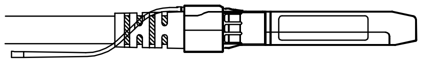
1.BACKSHELLS-ZINC DIE CAST WITH BRIGHT NICKEL PLATING
DELATCH-STAINLESS STEEL AND ZYTEL
CONNECTOR:
PRODUCT MATERIAL: NO. 3 ZINC ALLOY;
PLATING FILM REQUIREMENTS: NI150U "MIN CU150" MIN
HIGH TEMPERATURE TEST REQUIREMENTS: 80 ° C 120H
PCB-M6
RIVETS-STAINLESS STEEL

2.IMPEDANCE-100 OHMS DIFERENTIAL

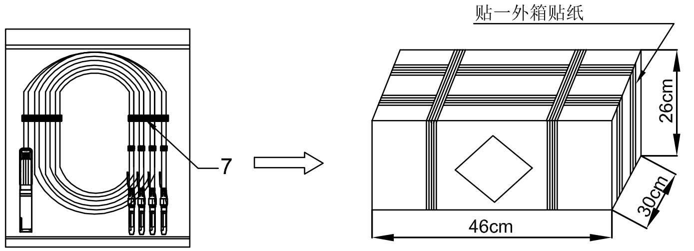
3.LEAD FREE NO ROHS EXEMPTIONS

2. PACKING METHOD:
1. EACH PIECE IS PACKED IN AN ANTI-STATIC BAG .SIZE:0.06MM*30"*40"
2. USE THE CARTON SPECIFIED IN THE PICTURE ON THE RIGHT,

3. REMARKS: ALL MATERIALS OF THIS PRODUCT ARE IN LINE WITH ROHS.



LENGTH	TOL.	AWG	OD (mm)
0. 5M	± 0. 03M	30	4. 5 ± 0. 2
1. 0M	± 0. 03M	30	4. 5 ± 0. 2
1. 0M	± 0. 03M	30	4. 5 ± 0. 2
1. 2M	± 0. 03M	30	4. 5 ± 0. 2
1. 5M	± 0. 03M	30	4. 5 ± 0. 2
2. 0M	± 0. 03M	30	4. 5 ± 0. 2
3. 0M	± 0. 05M	30	4. 5 ± 0. 2
4. 0M	± 0. 05M	26	5. 6 ± 0. 2
5. 0M	± 0. 08M	26	5. 6 ± 0. 2



8	TAIL CARD： Ø5.6*10mm BLACK	4	PCS
7	MAGIC BELT: SELF-ADHESIVE BLACK	6	PCS
6	CASING: Ø12.7*50MM RUBBER BLACK SLEEVE	1	PCS
5	STICKER: BLACK ON WHITE, TRANSPARENT FILM SELF-ADHESIVE	4	PCS
4	COPPER FOIL: W=5MM (GOOD ADHESION) THICKNESS 0.06MM	5	PCS
3	CONNECTOR: SFP+ (WITH PCB BOARD GOLD FINGER GOLD PLATED 30U")	4	SET
2	CONNECTOR: QSFP+ (WITH PCB BOARD GOLD FINGER GOLD PLATED 30U")	1	SET
1	UL20276 28AWG (1/0.32*1P+AE)*2P+AB (16/8/0.1TC), OUTER COVER: BLACK	4	PCS
项目	品名规格	数量	单位

深圳市凯鸿创电子科技有限公司
SHEN ZHEN KHC Electronic Technology CO.,LTD

APPROVED		DESIGN	STONE
REVIEW		CHECK	ELLA
SCALE	1:1	DATE	2019.08.08

MATERIAL NO.: KHCZQ-4SFP26XXXXX

CUSTOMER NO.:
100G_ZQSFP TO 4SFP_30AWG /26AWG

DRAW NO.:

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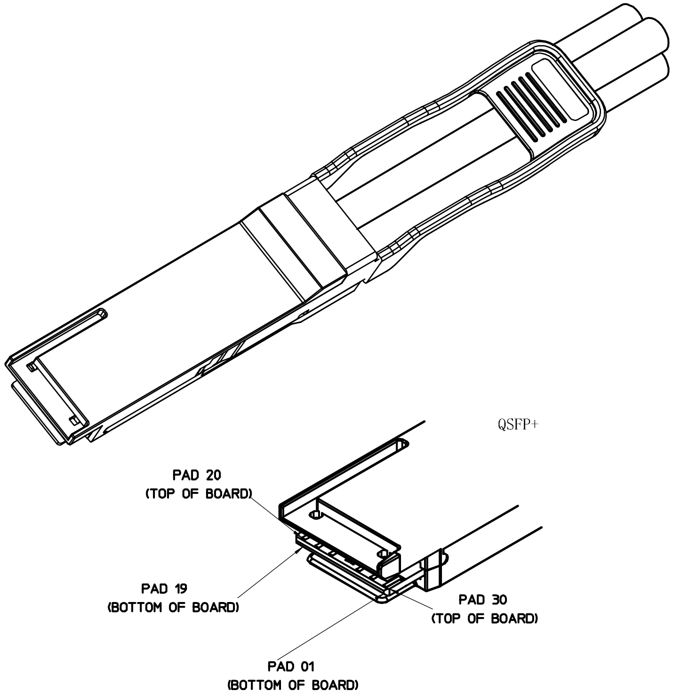
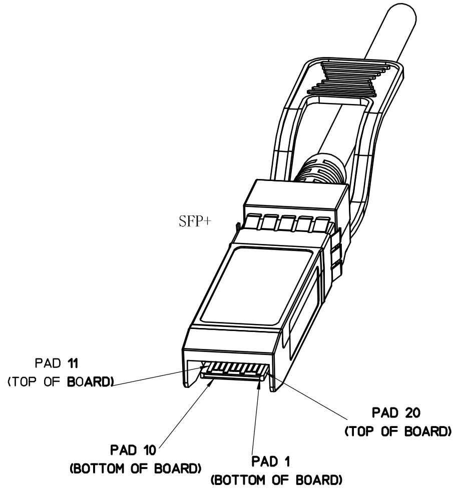
WIRING DIAGRAM				
QSFP+		SFP+		
PAD	SIGNAL	SIGNAL	PAD	PLUG
38	GND	GND		1
37	TX1- →	RD-	12	
36	TX1+ →	RD+	13	
16	GND	GND		
17	RX1+ ←	TD+	18	
18	RX1- ←	TD-	19	
04	GND	GND		2
02	TX2- →	RD-	12	
03	TX2+ →	RD+	13	
23	GND	GND		
22	RX2+ ←	TD+	18	
21	RX2- ←	TD-	19	
35	GND	GND		3
34	TX3- →	RD-	12	
33	TX3+ →	RD+	13	
13	GND	GND		
14	RX3+ ←	TD+	18	
15	RX3- ←	TD-	19	
07	GND	GND		4
05	TX4- →	RD-	12	
06	TX4+ →	RD+	13	
26	GND	GND		
25	RX4+ ←	TD+	18	
24	RX4- ←	TD-	19	





五、测试要求:

1.绝缘阻抗: 最小20M欧;

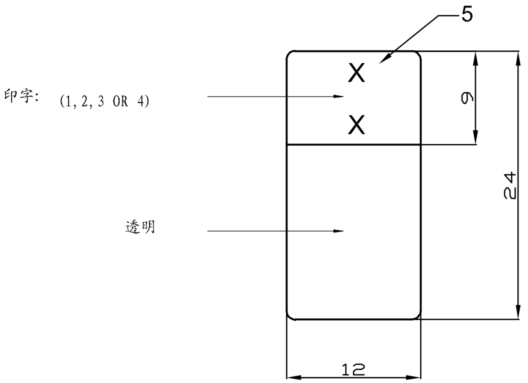
导通阻抗: 最大10欧;

高压测试: DC300V/10ms;

2.高频测试:

量测参数	标准规格
差分阻抗	100+/-5ohm
连接器阻抗	100+/-10ohm
对间延迟差	<50PS/m
对内延迟差	<21PS/m
差分延迟	5.2ns/m
衰减	Start - 50MHZ Stop - 7500MHZ Lim From -14db Lim To -28.4db

标签规格



LOW SPEED SIGNALS	
QSFP+	
PAD	SIGNAL
08	ModSelL
09	ResetL
10	VccRx
11	SCL
12	SDA
27	ModPrsL
28	IntL
29	VccTx
30	Vcc1
31	LPMode

LOW SPEED SIGNALS	
SFP+	
PAD	SIGNAL
02	Tx_Fault
03	Tx_Disable
04	SDA
05	SCL
06	Mod_ABS
07	RS0
08	Rx_LOS
09	RS1
15	VccR
16	VccT

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APPROVED		DESIGN	STONE	MATERIAL NO.: KHCZQ-4SFP26XXXXX		
REVIEW		CHECK	ELLA	CUSTOMER NO.: 100G_ZQSFP TO 4SFP_30AWG /26AWG		
SCALE	1:1	DATE	2019.08.08	DRAW NO.:		共2页 第2页